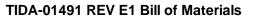
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 *01491





Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	!PCB1	1		TIDA-01491	Any	Printed Circuit Board	
2	C1	1	10uF	GCM31CC71E106KA03L	MuRata	CAP, CERM, 10 uF, 25 V, +/- 10%, X7S, AEC-Q200 Grade 1, 1206_190	1206_190
-	C2	1	22uF	GCM31CR70J226KE23L	MuRata	CAP, CERM, 22 µF, 6.3 V,+/- 10%, X7R, AEC-Q200 Grade 1, 1206	1206
	C3, C5	2	4.7uF	GCM21BC71E475KE36L	MuRata	CAP, CERM, 4.7 µF, 25 V,+/- 10%, X7S, AEC-Q200 Grade 1, 0805	0805
	C4, C6		0.1uF	CGA3E2X7R1E104K080AA	TDK	CAP, CERM, 0.1 µF, 25 V,+/- 10%, X7R, AEC-Q200 Grade 1, 0603	0603
	C7, C8, C9, C10	4	10uF	GCM21BR70J106KE22L	MuRata	CAP, CERM, 10 µF, 6.3 V,+/- 10%, X7R, AEC-Q200 Grade 1, 0805	0805
7	C11	1	0.033uF	CGA2B1X7R1E333K050BC	TDK	CAP, CERM, 0.033 uF, 25 V, +/- 10%, X7R, AEC-Q200 Grade 1, 0402	0402
8	C12, C13	2	0.01uF	CGA2B3X7R1H103K050BB	TDK	CAP, CERM, 0.01 uF, 50 V, +/- 10%, X7R, AEC-Q200 Grade 1, 0402	0402
9	C14	1	68pF	GCM1885C1H680JA16D	MuRata	CAP, CERM, 68 pF, 50 V, +/- 5%, C0G/NP0, AEC-Q200 Grade 1, 0603	0603
10	H1	1		GHR-08V-S	JST	Will add component to BOM. Useful for cables, nuts, etc. not in libraries	Housing receptacle
	H2, H3, H4, H5, H6, H7, H8, H9	8		SSHL-002T-P0.2	JST	Will add component to BOM. Useful for cables, nuts, etc. not in libraries	Terminal
12	J1	1		59S10H-40ML5-Z	Rosenberger	Connector, HF, 50 Ohm, TH	SMA Connector
13	J2, J3, J4	3		JMP-36-30X40SMT	Any	Jumper, SMT	shorting jumper, SMT
14	J5	1		BM08B-GHS-TBT(LF)(SN)(N)	JST Manufacturing	Header(shrouded), 1.25mm, 8x1, Tin, TH	Header(shrouded), 1.25mm, 8x1, TH
15	L1, L5	2	2.2uH	SRN2010TA-2R2M	Bourns	Inductor, Shielded, Ferrite, 2.2 uH, 1.2 A, 0.174 ohm, AEC-Q200 Grade 1, SMD	2.0x1.6x1.0mm
16	L2, L4, L8	3		BLM18HE152SN1D	MuRata	Ferrite Bead, 1500 ohm @ 100 MHz, 0.5 A, 0603	0603
	L3	1	600 ohm	BLM18KG601SN1D	MuRata	Ferrite Bead, 600 ohm @ 100 MHz, 1.3 A, 0603	0603
18	L7	1	10uH	LQH3NPZ100MJRL	MuRata	Inductor, Wirewound, Ferrite, 10 uH, 0.81 A, 0.288 ohm, AEC-Q200 Grade 1, SMD	3x3mm
19	LBL1	1		THT-14-423-10	Brady		PCB Label 0.650 x 0.200 inch
	R1	1	4.12k	ERA-3AEB4121V	Panasonic	RES, 4.12 k, 0.1%, 0.1 W, AEC-Q200 Grade 0, 0603	0603
21	R2	1	11k	CRCW040211K0JNED	Vishay-Dale	RES, 11 k, 5%, 0.063 W, AEC-Q200 Grade 0, 0402	0402
	R3, R5, R9, R11	4	150k	ERJ-2RKF1503X	Panasonic	RES, 150 k, 1%, 0.1 W, AEC-Q200 Grade 0, 0402	0402
	R4, R7	2	470k	ERJ-2RKF4703X	Panasonic	RES, 470 k, 1%, .1 W, AEC-Q200 Grade 0, 0402	0402
	R6	1	300k	CRCW0402300KFKED	Vishay-Dale	RES, 300 k, 1%, 0.063 W, AEC-Q200 Grade 0, 0402	0402
	R8	1	698k	ERJ-2RKF6983X	Panasonic	RES, 698 k, 1%, .1 W, AEC-Q200 Grade 0, 0402	0402
	R10	1	210k	ERJ-2RKF2103X	Panasonic	RES, 210 k, 1%, 0.1 W, AEC-Q200 Grade 0, 0402	0402
27	U1	1		TPS62160QDSGRQ1	Texas Instruments	3V-17V 1A Automotive Step-Down Converters in 2x2SON, DSG0008A (WSON-8)	DSG0008A
28	U2	1		TPS65000TRTERQ1	Texas Instruments	2.25MHz Step-Down Converter with Dual LDOs & SVS Power Management IC (PMIC), RTE0016C (WQFN-16)	RTE0016C
29	FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	N/A

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